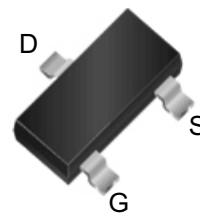


### N-Channel, 20V, 3.2A, Power MOSFET

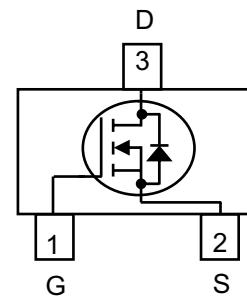
<b>V<sub>DS</sub> (V)</b>	<b>Typical R<sub>DS(on)</sub> (mΩ)</b>
20	40 @ V <sub>GS</sub> =4.5V
	47 @ V <sub>GS</sub> =2.5V
	55 @ V <sub>GS</sub> =1.8V



**SOT-23**

### Descriptions

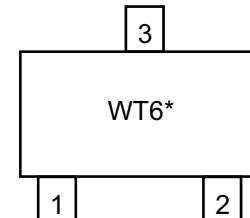
The WNM2016 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM2016 is Pb-free and Halogen-free.



**Configuration (Top View)**

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-23



WT6 = Device Code

\* = Month (A~Z)

### Marking

### Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch

### Order Information

<b>Device</b>	<b>Package</b>	<b>Shipping</b>
WNM2016-3/TR	SOT-23	3000/Tape&Reel

<b>ABSOLUTE MAXIMUM RATINGS</b> TA = 25 °C, unless otherwise noted						
Parameter	Symbol	10 S	Steady State	Unit		
Drain-Source Voltage	V <sub>DS</sub>	20		V		
Gate-Source Voltage	V <sub>GS</sub>	±8				
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	3.2	2.9	A	
	T <sub>A</sub> =70°C		2.5	2.3		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.8	0.7	W	
	T <sub>A</sub> =70°C		0.5	0.4		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>b</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	2.9	2.7	A	
	T <sub>A</sub> =70°C		2.3	2.1		
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.6	0.5	W	
	T <sub>A</sub> =70°C		0.4	0.3		
Pulsed Drain Current <sup>c</sup>	I <sub>DM</sub>	10		A		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C		

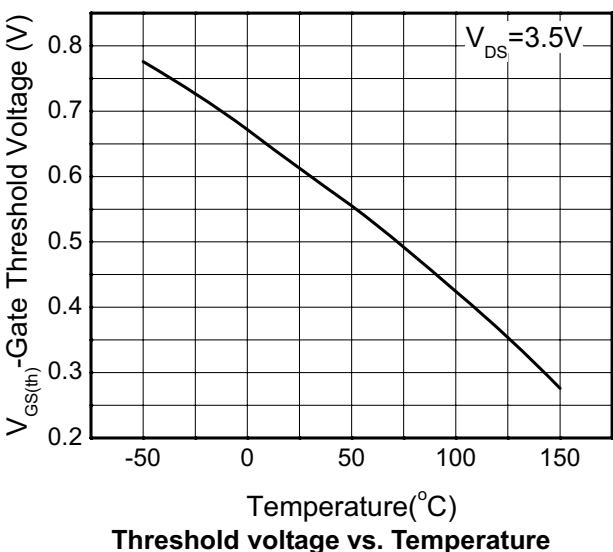
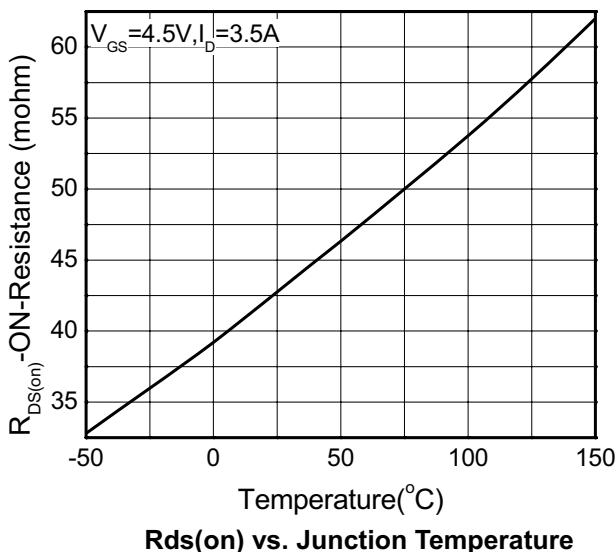
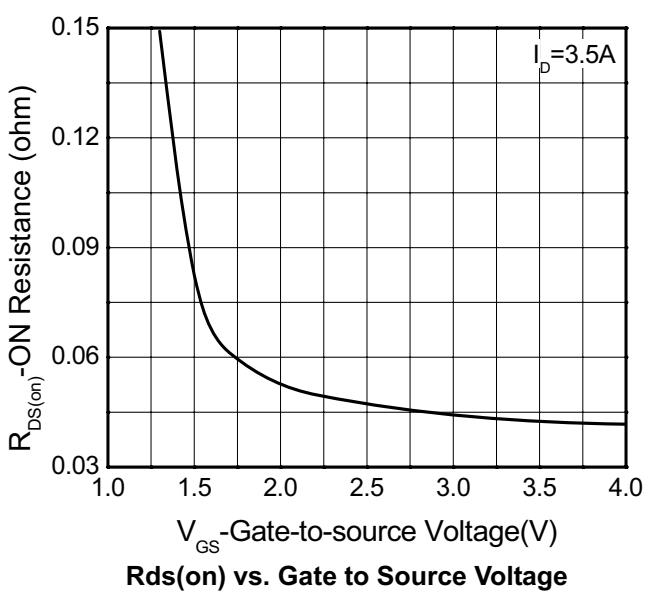
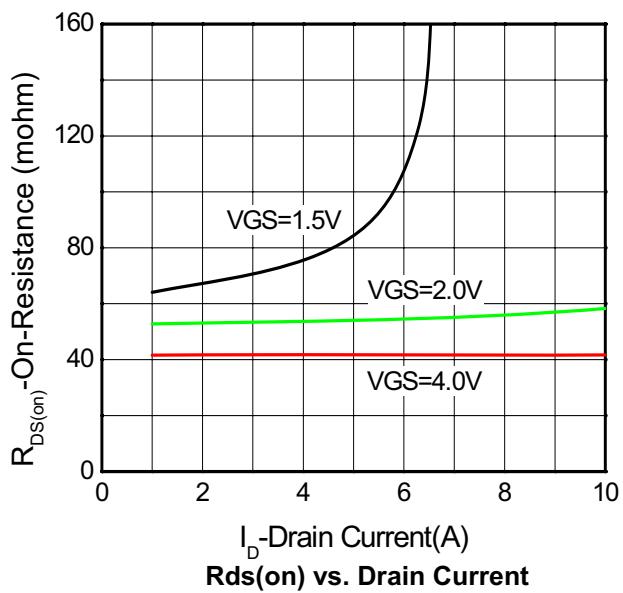
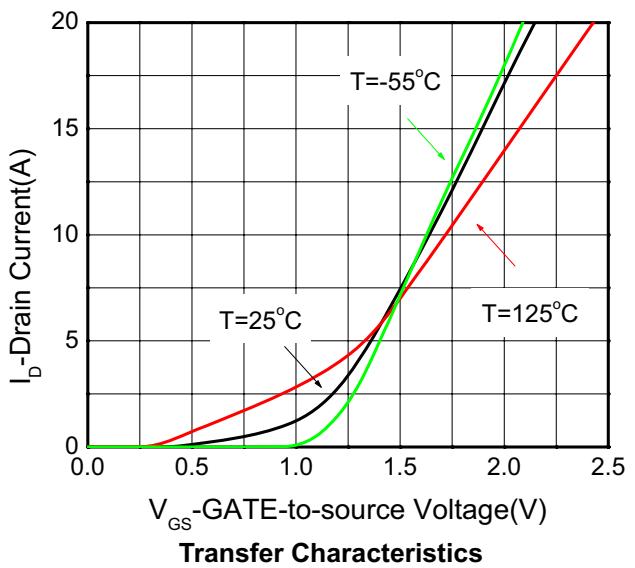
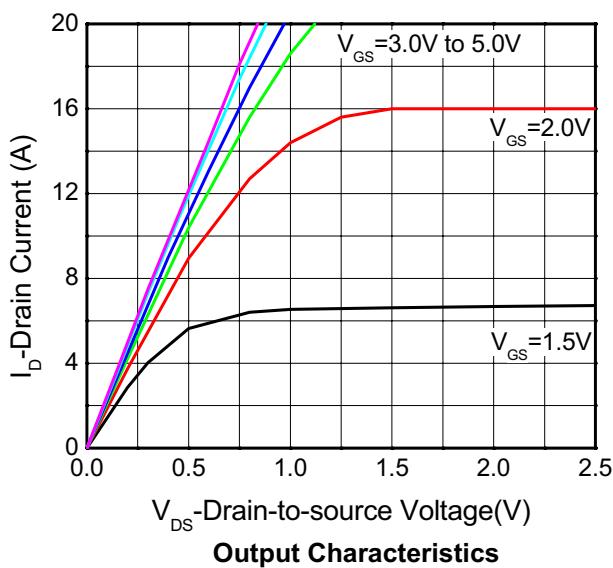
<b>THERMAL RESISTANCE RATINGS</b>					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t ≤ 10 s	R <sub>θJA</sub>	125	150	°C/W
	Steady State		140	175	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	t ≤ 10 s	R <sub>θJA</sub>	150	180	°C/W
	Steady State		165	210	
Junction-to-Case Thermal Resistance	Steady State	R <sub>θJC</sub>	60	76	

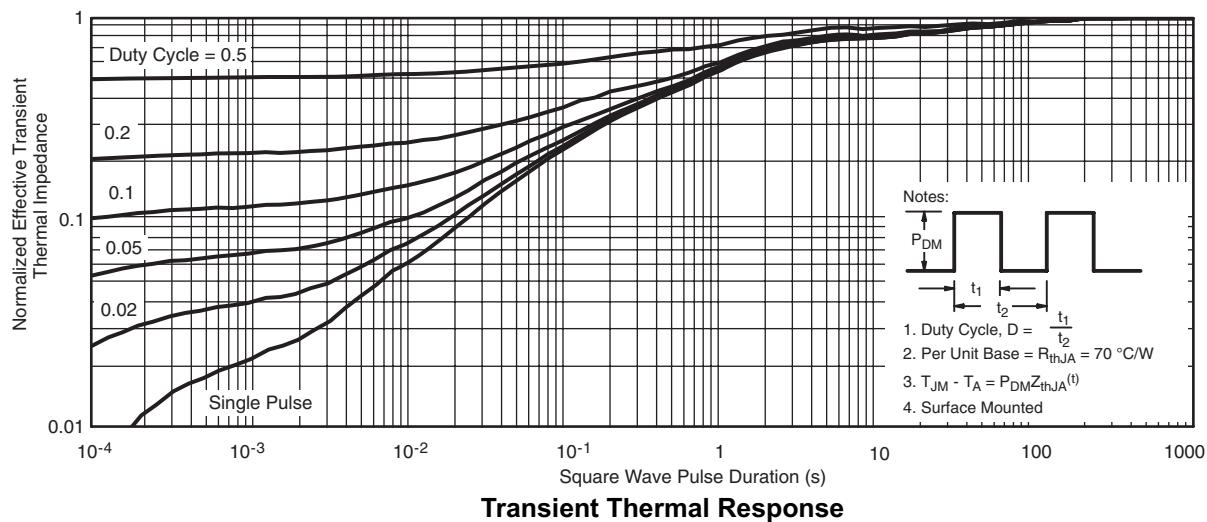
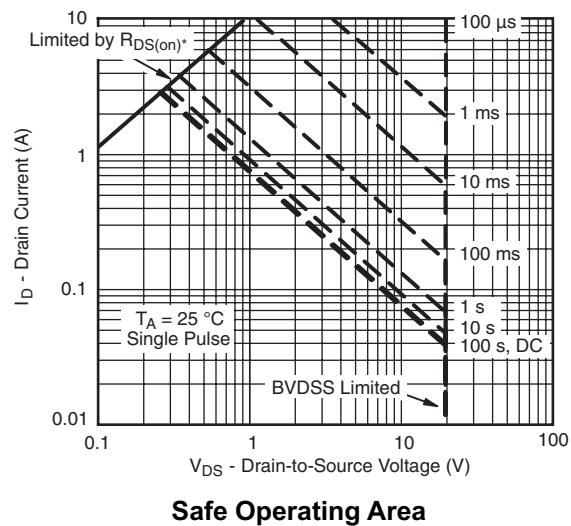
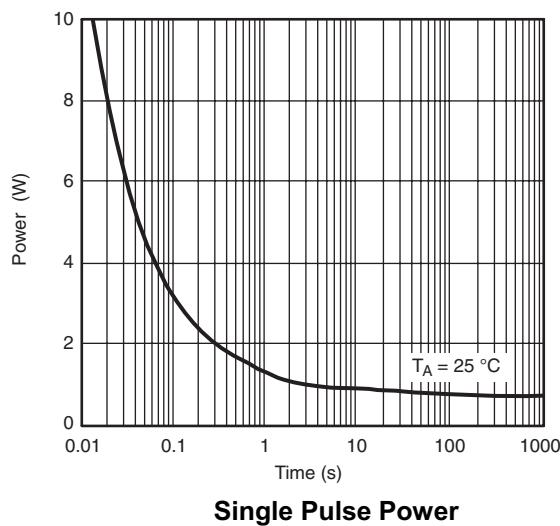
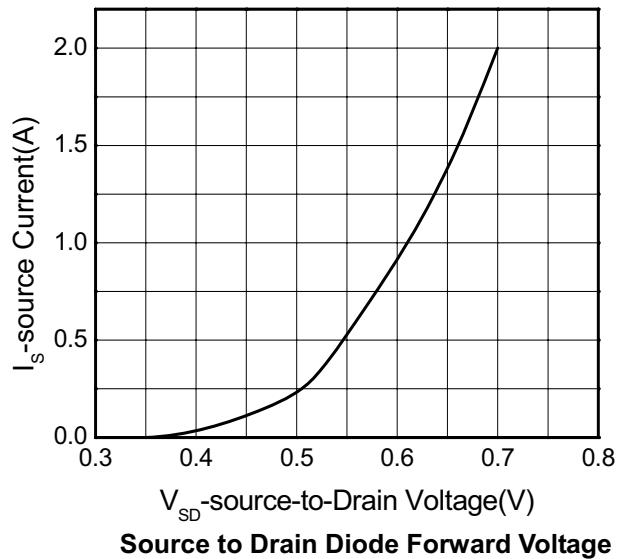
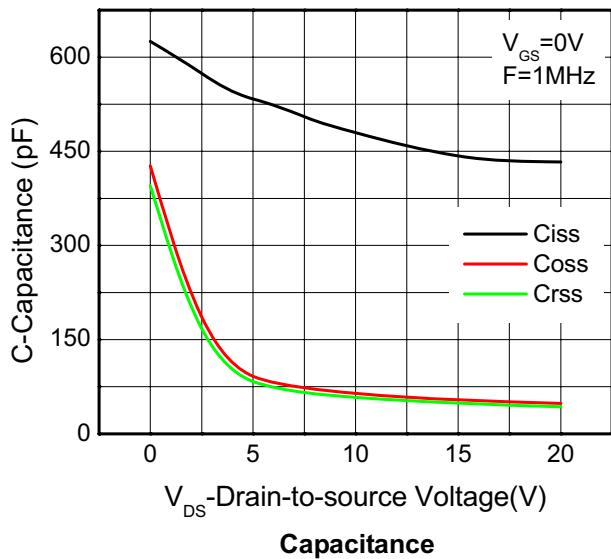
- a Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.
- b Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.
- c Repetitive rating, pulse width limited by junction temperature, t<sub>p</sub>=10μs, Duty Cycle=1%
- d Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.

**Electronics Characteristics**

(Ta=25°C, unless otherwise noted)

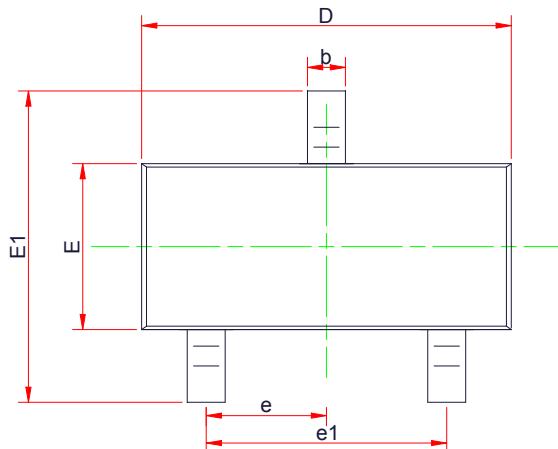
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250uA	20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0V			1	uA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±8.0V			±100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250uA	0.4	0.6	1	V
Drain-to-source On-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.6A		40	47	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3.1A		47	55	
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 1.0A		55	66	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 3.1A		8.5		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 10 V		500		pF
Output Capacitance	C <sub>OSS</sub>			62		
Reverse Transfer Capacitance	C <sub>RSS</sub>			58		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.1 A		8.5		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			0.45		
Gate-to-Source Charge	Q <sub>GS</sub>			0.65		
Gate-to-Drain Charge	Q <sub>GD</sub>			3.1		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	td(ON)	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V, R <sub>L</sub> =3.5Ω, R <sub>G</sub> =6 Ω		12		ns
Rise Time	tr			20.8		
Turn-Off Delay Time	td(OFF)			38.8		
Fall Time	tf			10.8		
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Forward Recovery Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.0A		0.62	1.5	V

**Typical Performance Graph**

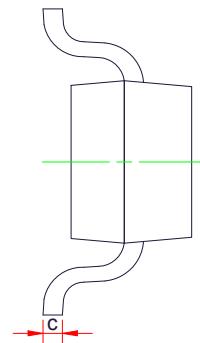


## Package Outline Dimension

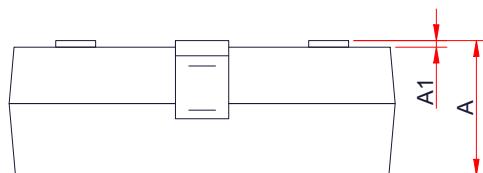
SOT-23



TOP VIEW

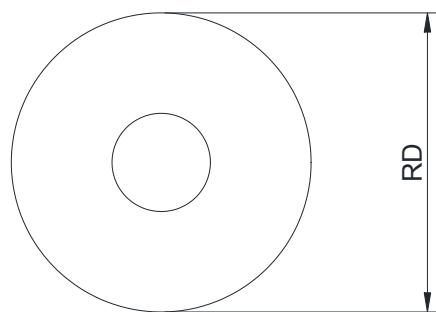
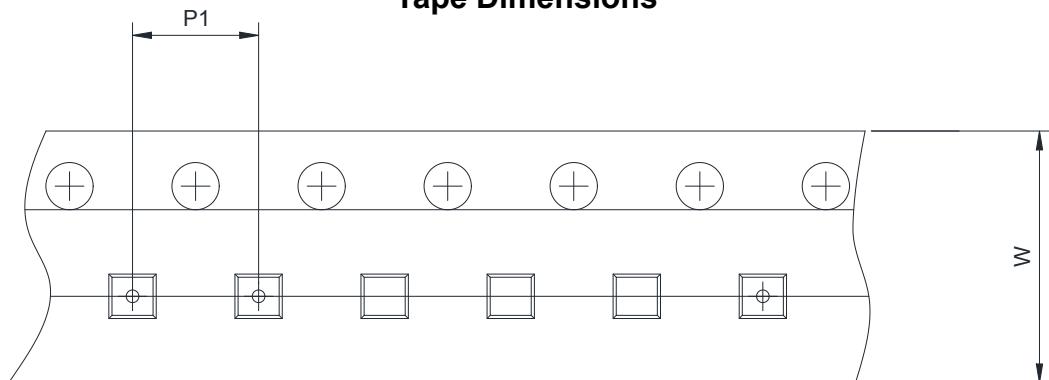
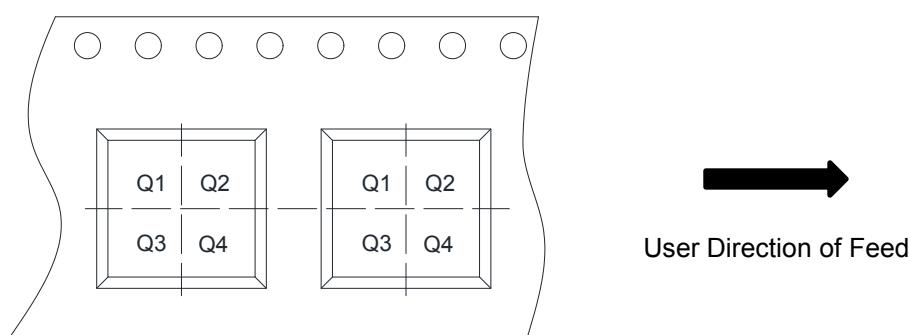


SIDE VIEW



SIDE VIEW

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.89	1.10	1.30
A1	0.00	-	0.10
b	0.30	0.43	0.55
c	0.05	-	0.20
D	2.70	2.90	3.10
E	1.15	1.33	1.50
E1	2.10	2.40	2.70
e	0.95 Typ.		
e1	1.70	1.90	2.10

**TAPE AND REEL INFORMATION****Reel Dimensions****Tape Dimensions****Quadrant Assignments For PIN1 Orientation In Tape**

RD	Reel Dimension	<input checked="" type="checkbox"/> 7inch	<input type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input checked="" type="checkbox"/> 8mm	<input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input checked="" type="checkbox"/> 4mm <input type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input checked="" type="checkbox"/> Q3 <input type="checkbox"/> Q4